

	L #	Hits	Search Text	DBs
1	L1	535497	mold\$4	EPO; JPO; DERWE NT; IBM_TDB
2	L2	268521	etch\$4	EPO; JPO; DERWE NT; IBM_TDB
3	L3	612511	silicon or wafer	EPO; JPO; DERWE NT; IBM_TDB
4	L4	1409592	hole or orifice	EPO; JPO; DERWE NT; IBM_TDB
5	L5	80	1 and 2 and 3 and 4	EPO; JPO; DERWE NT; IBM_TDB
6	L6	1303502	substrate	EPO; JPO; DERWE NT; IBM_TDB
7	L7	1623863	rear or back or backside or (other or second or reverse or bottom) adj2 (side or surface)	EPO; JPO; DERWE NT; IBM_TDB

	L #	Hits	Search Text	DBs
8	L8	90868	(4 or 6) near 5 7	EPO; JPO; DERWE NT; IBM_TDB
9	L9	59	1 and 2 and 8	EPO; JPO; DERWE NT; IBM_TDB
10	L10	55	9 not 5	EPO; JPO; DERWE NT; IBM_TDB
11	L11	340376	(metal\$4 near3 deposit\$6) or electro or electroform\$8 or electrocoat\$8 or electrodeposit\$8 or electrolytic\$8	EPO; JPO; DERWE NT; IBM_TDB
12	L12	537186	nickel or ni	EPO; JPO; DERWE NT; IBM_TDB
13	L13	2922	1 and (3 or 6) and (11 or 12)	EPO; JPO; DERWE NT; IBM_TDB
14	L14	245	2 and 13	EPO; JPO; DERWE NT; IBM_TDB

	L #	Hits	Search Text	DBs
15	L15	31	14 and 7	EPO; JPO; DERWE NT; IBM_TDB
16	L16	18	15 not (5 or 9)	EPO; JPO; DERWE NT; IBM_TDB
17	L17	1158	1 and 3 and (11 or 12)	EPO; JPO; DERWE NT; IBM_TDB
18	L18	85	2 and 17	EPO; JPO; DERWE NT; IBM_TDB
19	L19	57	18 not (5 or 9 or 15)	EPO; JPO; DERWE NT; IBM_TDB